

IN THE CLAIMS:

Please CANCEL claims 10-16 without prejudice or disclaimer. Please AMEND various claims in accordance with the following:

1. (Currently Amended) A manufacturing method for an optical waveguide device, comprising:
 - forming an optical waveguide in a substrate having an electro-optic effect, said substrate having upper, lower, and side surfaces;
 - forming an SiO₂ film on said substrate;
 - forming silicon (Si) films on said SiO₂ film, the lower surface of said substrate, and at least a part of the side surface of said substrate to thereby make a conduction between said Si ~~films film~~-formed on said SiO₂ film and said Si ~~films film~~-formed on the lower surface of said substrate;
 - applying a photoresist to said Si ~~films film~~-formed on said SiO₂ film;
 - patterning said photoresist so that a portion of said photoresist corresponding to said optical waveguide is left attached on said Si ~~films film~~;
 - forming a groove on said substrate along said optical waveguide by reactive ion etching;
 - and
 - removing said photoresist and said Si films.
2. (Previously Presented) The manufacturing method according to claim 1, wherein said substrate comprises a LiNbO₃ substrate, and forming said optical waveguide comprises thermally diffusing titanium (Ti) in said LiNbO₃ substrate.
3. (Previously Presented) The manufacturing method according to claim 1, wherein said forming said Si films is performed by sputtering.
4. (Original) The manufacturing method according to claim 1, wherein said photoresist comprises a conductive photoresist.
5. – 16. (Cancelled).